

L Number	Hits	Search Text	DB	Time stamp
-	1599	257/783	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 16:22
-	2097	257/686	USPAT	2004/06/30 11:34
-	1188	257/686 and (adhesive or glue)	USPAT	2004/07/19 18:35
-	1327	257/783	USPAT	2004/06/30 11:18
-	2628	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 11:34
-	1188	257/686 and (adhesive or glue)	USPAT	2004/06/30 11:35
-	1440	257/686 not (257/686 and (adhesive or glue))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 15:55
-	1859	257/707	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 16:17
-	1995	438/108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 16:55
-	929	438/109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 17:13
-	3657	361/760	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 20:12
-	1442	361/760 and (adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 20:12
-	3657	361/760	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 20:12
-	3315	361/760	USPAT	2004/06/30 20:12
-	1442	361/760 and (adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 20:12
-	1945	361/760 not (361/760 and (adhesive or glue).)	USPAT	2004/06/30 20:18
-	270	361/760 not (361/760 and (adhesive or glue).)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/30 20:19
-	2649	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 16:23
-	2111	257/686	USPAT	2004/07/13 16:23
-	1485	257/686 and (adhesive or glue or insert\$3 or under near fill\$3)	USPAT	2004/07/13 18:04
-	1	"5343075".PN.	USPAT	2004/07/13 18:39
-	1	"5952725".PN.	USPAT	2004/07/13 18:52

-	1	"6049124".PN.	USPAT	2004/07/13 19:15
-	1	"6351028".PN.	USPAT	2004/07/13 19:16
-	1	"6351028".PN.	USPAT	2004/07/13 19:16
-	1	"6576992".PN.	USPAT	2004/07/13 19:16
-	1	"5805422".PN.	USPAT	2004/07/13 19:48
-	1	"6225688".PN.	USPAT	2004/07/13 19:49
-	1	"6262895".PN.	USPAT	2004/07/13 19:49
-	1	"6005778".PN.	USPAT	2004/07/13 19:54
-	1	"6100594".PN.	USPAT	2004/07/13 19:55
-	1	"6271598".PN.	USPAT	2004/07/13 19:55
-	1	"6333562".PN.	USPAT	2004/07/13 20:04
-	1	"6351028".PN.	USPAT	2004/07/13 20:04
-	1	"6359340".PN.	USPAT	2004/07/13 20:04
-	1	"6441496".PN.	USPAT	2004/07/13 20:04
-	1	"6545365".PN.	USPAT	2004/07/13 20:04
-	1	"6555902".PN.	USPAT	2004/07/13 20:05
-	1485	257/686 and (adhesive or glue or insert\$3 or under near fill\$3)	USPAT	2004/07/15 19:56
-	1346	257/777 and (adhesive or glue or insert\$3 or under near fill\$3)	USPAT	2004/07/15 20:36
-	1485	257/686 and (adhesive or glue or insert\$3 or under near fill\$3)	USPAT	2004/07/15 19:56
-	630	(257/777 and (adhesive or glue or insert\$3 or under near fill\$3)) not (257/686 and (adhesive or glue or insert\$3 or under near fill\$3))	USPAT	2004/07/15 19:57
-	3461	(361/760 or 438/108 or 438/109) and (adhesive or glue or insert\$3 or under near fill\$3)	USPAT	2004/07/15 20:37
-	2181	(361/760) and (adhesive or glue or insert\$3 or under near fill\$3)	USPAT	2004/07/15 20:37
-	1774	((361/760) and (adhesive or glue or insert\$3 or under near fill\$3)) not ((257/777 and (adhesive or glue or insert\$3 or under near fill\$3)) or (257/686 and (adhesive or glue or insert\$3 or under near fill\$3)))	USPAT	2004/07/19 17:37
-	1		USPAT	2004/07/19 11:34
-	1		USPAT	2004/07/19 11:34
-	1		USPAT	2004/07/19 11:34
-	1		USPAT	2004/07/19 11:34
-	1		USPAT	2004/07/19 11:35
-	1		USPAT	2004/07/19 11:35
-	1		USPAT	2004/07/19 11:35
-	1		USPAT	2004/07/19 11:35
-	1		USPAT	2004/07/19 11:36
-	1		USPAT	2004/07/19 11:36
-	1		USPAT	2004/07/19 11:36
-	1		USPAT	2004/07/19 11:50
-	1		USPAT	2004/07/19 11:51
-	2663	((361/760 or 438/108 or 438/109) and (adhesive or glue or insert\$3 or under near fill\$3)) not ((257/777 and (adhesive or glue or insert\$3 or under near fill\$3)) or (257/686 and (adhesive or glue or insert\$3 or under near fill\$3)))	USPAT	2004/07/19 17:37
-	1774	((361/760) and (adhesive or glue or insert\$3 or under near fill\$3)) not ((257/777 and (adhesive or glue or insert\$3 or under near fill\$3)) or (257/686 and (adhesive or glue or insert\$3 or under near fill\$3)))	USPAT	2004/07/19 18:16

-	889	(((361/760 or 438/108 or 438/109) and (adhesive or glue or insert\$3 or under near fill\$3)) not ((257/777 and (adhesive or glue or insert\$3 or under near fill\$3)) or (257/686 and (adhesive or glue or insert\$3 or under near fill\$3)))) not (((361/760) and (adhesive or glue or insert\$3 or under near fill\$3)) not ((257/777 and (adhesive or glue or insert\$3 or under near fill\$3)) or (257/686 and (adhesive or glue or insert\$3 or under near fill\$3))))	USPAT	2004/07/19 17:38
-	143	mother near (chip or die or IC or semiconductor) and (adhesive or glue or insert\$3 or under near fill\$3)	USPAT	2004/07/19 18:24
-	48	"4764804" and (adhesive or glue or insert\$3 or under near fill\$3)	USPAT	2004/07/19 18:24
-	2651	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/19 18:35
-	1422	257/686 and (adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/19 18:36
-	1229	257/686 not (257/686 and (adhesive or glue))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/19 18:36
-	1	5696031.pn.	USPAT	2004/07/20 11:16
-	1899	(semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with cover\$3 with side with (semiconductor or die or chip or IC)	USPAT	2004/07/20 14:03
-	1		USPAT	2004/07/20 11:47
-	1		USPAT	2004/07/20 11:48
-	1		USPAT	2004/07/20 11:51
-	1		USPAT	2004/07/20 11:51
-	1		USPAT	2004/07/20 11:51
-	1		USPAT	2004/07/20 11:52
-	1		USPAT	2004/07/20 11:53
-	1		USPAT	2004/07/20 11:53
-	1		USPAT	2004/07/20 11:55
-	1		USPAT	2004/07/20 11:56
-	1		USPAT	2004/07/20 11:56
-	40	4,971,930 5,530,282 6,512,219	USPAT	2004/07/22 13:36
-	29	"5224021"	USPAT	2004/07/20 13:58
-	29	"5801439"	USPAT	2004/07/20 13:58
-	1		USPAT	2004/07/20 14:02
-	1		USPAT	2004/07/20 14:02
-	1		USPAT	2004/07/20 14:02
-	1		USPAT	2004/07/20 14:02
-	13450	(semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with cover\$3 with (semiconductor or die or chip or IC)	USPAT	2004/07/20 14:04
-	1730	(semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with cover\$3 near (semiconductor or die or chip or IC)	USPAT	2004/07/20 14:04
-	73010	(semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U")	USPAT	2004/07/20 14:05
-	6113	(semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shap\$2 or formed)	USPAT	2004/07/20 14:06

-	4774	(semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)	USPAT	2004/07/20 14:09
-	4763	(semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") adj1 (shaped)	USPAT	2004/07/20 14:10
-	817	((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "257"	USPAT	2004/07/20 18:48
-	357	((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "438"	USPAT	2004/07/20 18:11
-	581	((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "361"	USPAT	2004/07/20 18:15
-	1		USPAT	2004/07/20 18:20
-	1		USPAT	2004/07/20 18:21
-	1		USPAT	2004/07/20 18:21
-	1		USPAT	2004/07/20 18:21
-	1		USPAT	2004/07/20 18:21
-	1		USPAT	2004/07/20 18:21
-	1		USPAT	2004/07/20 18:21
-	1		USPAT	2004/07/20 18:21
-	1		USPAT	2004/07/20 18:23
-	1		USPAT	2004/07/20 18:24
-	1		USPAT	2004/07/20 18:24
-	1		USPAT	2004/07/20 18:24
-	1		USPAT	2004/07/20 18:24
-	1		USPAT	2004/07/20 18:24
-	1		USPAT	2004/07/20 18:24
-	1		USPAT	2004/07/20 18:24
-	817	((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "257"	USPAT	2004/07/20 18:48
-	4774	((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped))	USPAT	2004/07/20 18:48
-	3452	((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped))) not (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "438") or (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "361") or (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "257"))	USPAT	2004/07/20 18:49
-	591	((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped))) not (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "438") or (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "361") or (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "257")) and "174"	USPAT	2004/07/20 18:57

-	1848	(((((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped))) not (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "438") or (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "361") or (((semiconductor or die or chip or IC) and (wir\$3 or conduct\$3 or metal\$7 or lead) with ("C" or "U") near (shaped)) and "257")))) and "29"	USPAT	2004/07/20 19:33
-	640	257/726	USPAT	2004/07/20 19:46
-	1131	257/727	USPAT	2004/07/20 20:04
-	2034	257/777	USPAT	2004/07/21 14:13
-	1		USPAT	2004/07/20 20:42
-	1		USPAT	2004/07/20 20:43
-	1		USPAT	2004/07/20 20:43
-	1		USPAT	2004/07/20 20:43
-	15	"5514613"	USPAT	2004/07/21 14:37
-	42	chris near chu	USPAT	2004/07/21 14:37
-	1		USPAT	2004/07/21 15:56
-	1		USPAT	2004/07/21 15:56
-	1		USPAT	2004/07/21 15:57
-	1		USPAT	2004/07/21 15:57
-	1		USPAT	2004/07/21 15:57
-	1		USPAT	2004/07/21 15:57
-	1		USPAT	2004/07/21 15:57
-	1517	Nakazato	USPAT	2004/07/21 21:00
-	3	4,971,930.pn.	USPAT	2004/07/22 13:54
		5,530,282.pn.		
		6,512,219.pn.		
-	4	5,440,231.pn.	USPAT	2004/07/22 13:58
		6,114,770.pn.		
		6,353,265.pn.		
		6,369,595.pn.		
-	1		USPAT	2004/07/22 13:56
-	1		USPAT	2004/07/22 13:56
-	1		USPAT	2004/07/22 13:56
-	1		USPAT	2004/07/22 13:56
-	1		USPAT	2004/07/22 13:56
-	1		USPAT	2004/07/22 13:56
-	1		USPAT	2004/07/22 13:56
-	1		USPAT	2004/07/22 13:56
-	1		USPAT	2004/07/22 13:57
-	1		USPAT	2004/07/22 13:58
-	36	"5302849"	USPAT	2004/07/22 14:05
-	3179	257/666	USPAT	2004/07/22 14:05
-	2660	257/666 and lead	USPAT	2004/07/22 14:06
-	1776	257/666 and lead and pad	USPAT	2004/07/22 18:18
-	2269	(semiconductor or die or chip or IC) and (pad or terminal or contact\$2) with (both or dual) near surfaces	USPAT	2004/07/22 18:24
-	2232	(semiconductor or die or chip or IC) and (pad or terminal or contact\$2) with (both) near surfaces	USPAT	2004/07/22 18:21
-	419	(semiconductor or die or chip or IC) and (pad or terminal or contact\$2) near (both or dual) near surfaces	USPAT	2004/07/22 18:22
-	438	(semiconductor or die or chip or IC) and (pad or terminal or contact\$2) with (both or dual) near surfaces with (semiconductor or die or chip or IC)	USPAT	2004/07/22 18:44
-	4	"6340845"	USPAT	2004/07/22 18:58
-	9	"6222212"	USPAT	2004/07/22 18:58
-	1		USPAT	2004/07/23 00:07
-	1		USPAT	2004/07/23 00:07
-	1		USPAT	2004/07/23 00:08
-	1		USPAT	2004/07/23 00:08
-	1		USPAT	2004/07/23 00:09

-	1		USPAT	2004/07/23 00:09
-	1		USPAT	2004/07/23 00:09
-	58	"5331235"	USPAT	2004/07/23 00:27